



**The NPM-W2 combines accurate component placement, precise SPI and AOI inspection and reproductive adhesive dispensing in one high-speed solution.**

## **NPM-W2 / NPM-W2S**

Higher productivity and quality thanks to the integration of printing, placement and inspection processes make the NPM-W2 one of the most flexible and versatile pick-and-place solutions on the market. This machine provides the user with a tool that allows him to choose between high speed or high accuracy, depending on the PCB requirements. In addition, the NPM-W2 is optimised for larger boards and larger components, such as PCBs up to 750 x 550 mm and components up to 150 x 25 x 30 mm (L,W,H). For high productivity, dual lanes can be used. Features The multifunctional NPM-W2 is equipped with a 16-nozzle head and can place 42,000 components. 120 feeders can be mounted. Additionally, the NPM-W2 can automatically inspect solder depots and components according to the production data. As a third function, the NPM can be fitted with the conventional HDF discharge mechanism, which ensures high-quality non-contact dispensing with a screw valve-dispenser.

### **Key Features**

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Equipped with a 16-nozzle head and can place 42,000 components

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Automatic inspection of solder depots and components according to the production data

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HDF discharge mechanism compatible, which ensures high-quality non-contact dispensing with a screw valve-dispenser



## NPM-W2 / NPM-W2S

<https://ap.connect.panasonic.com/id/en/products/smart-factory/npm-w2-npm-w2s>

<b>PCB dimensions (mm)</b>	Single-lane
	Batch mounting
	2-position mounting
	Dual-lane
	Dual transfer (Batch)
	Dual transfer (2-position)
	Single transfer (Batch)
	Single transfer (2-position)
<b>Placement Head max Speed</b>	42 000cph (0.094 s/ chip)
<b>Placement Head Placement Accuracy (Cpk<math>\geq</math>1)</b>	$\pm 40 \mu\text{m}$ / chip
<b>Placement Head Component Dimensions (mm)</b>	0402 chip ~ L 6 x W 6 x T 3
<b>Taping</b>	Tape : 4 / 8 / 12 / 16 / 24 / 32 / 44 / 56 mm
	Max.120 (Tape: 4, 8 mm)
<b>Dispensing Head</b>	Dispensing speed:
	Dot dispensing: 0.16 s/dot (Condition : XY=10 mm, Z=less than 4 mm movement, No $\theta$ rotation)
	Draw dispensing: 4.25 s/component (Condition : 30 mm x 30 mm corner dispensing)*9
	Adhesive position accuracy (Cpk $\geq$ 1)
	Dot Dispensing: $\pm 75 \mu\text{m}$ /dot
	Draw Dispensing: $\pm 100 \mu\text{m}$ /component
	Applicable components
	Dot Dispensing: 1608 chip to SOP,PLCC,QFP, Connector, BGA, CSP
	Draw Dispensing: BGA, CSP
	2D inspection head (A)
<b>Resolution</b>	18 $\mu\text{m}$
<b>View Size (mm)</b>	44.4 x 37.2
<b>Inspection Processing Time</b>	Solder Inspection 0.35s/ View size
	Component Inspection 0.5s/ View size
<b>Inspection Object</b>	Solder Inspection
	Chip component: 100 $\mu\text{m}$ x 150 $\mu\text{m}$ or more (0603 or more)
	Package component: $\phi 150 \mu\text{m}$ or more
	Component Inspection:
	Square chip (0603 or more), SOP, QFP (a pitch of 0.4mm or more), CSP, BGA, Aluminum electrolysis capacitor, Volume, Trimmer, Coil, Connector

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<b>Inspection Items</b>	Solder Inspection: Oozing, blur, misalignment, abnormal shape, bridging
	Component Inspection: Missing, shift, flipping, polarity, foreign object inspection
<b>Inspection Position Accuracy</b>	± 20 μm
<b>No of Inspection</b>	Solder Inspection : Max. 30 000 pcs./machine (No. of components :Max. 10 000 pcs./machine)
	Component Inspection: Max. 10 000 pcs./machine